



**Please note that Cypress is an Infineon Technologies Company.**

The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

**Continuity of document content**

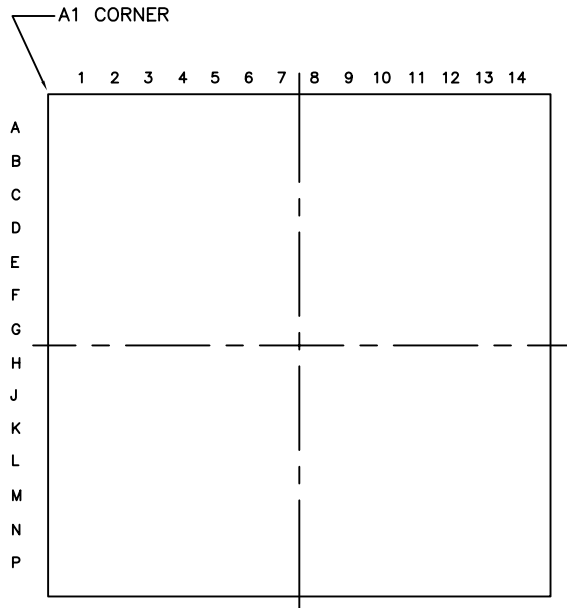
The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

**Continuity of ordering part numbers**

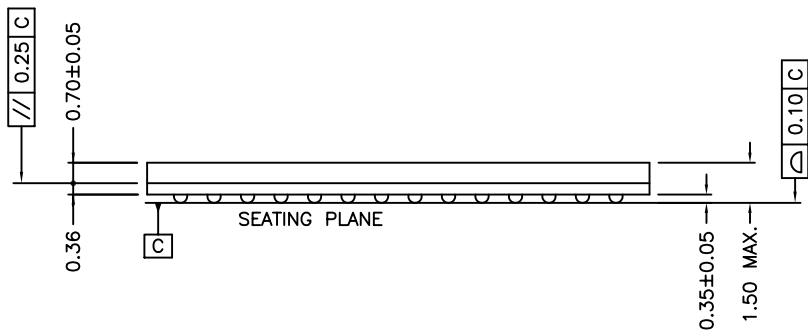
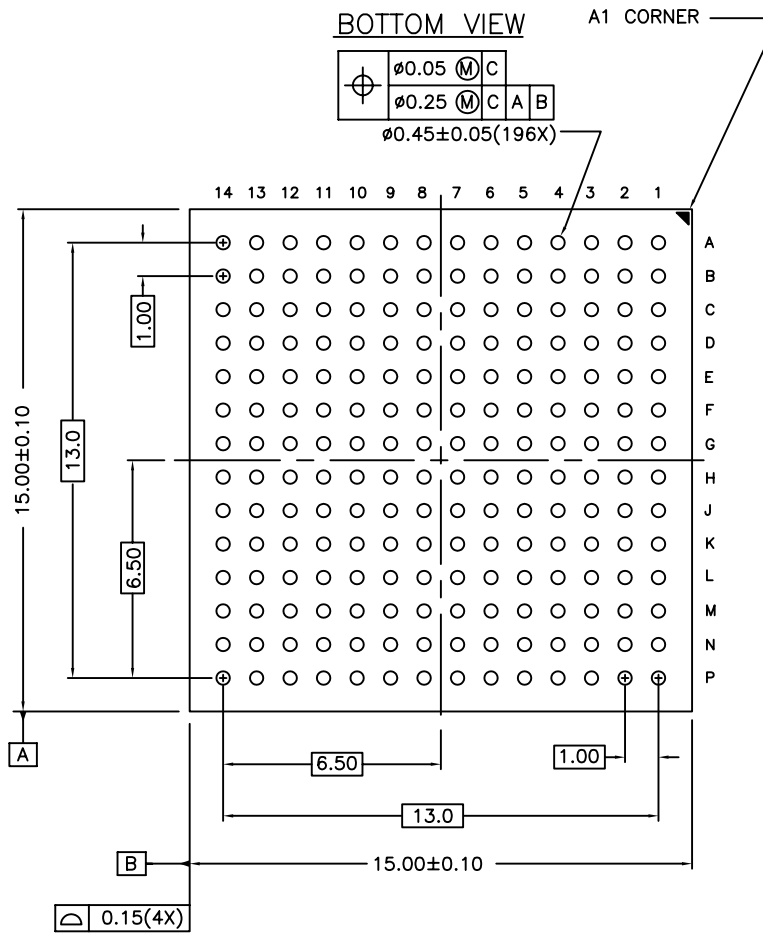
Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	112416	NEW RELEASE	12/19/01	N/A
1	-	*A	115633	ADD SUBSTRATE DIM./ ADD MOLD CAP DIM./ CHG. BALL HEIGHT DIM./ CHG. PKG. BODY TOLERANCE	05/14/02	N/A
1	-	*B	2811684	Changed Template and Title from 196 FBGA (15x15x1.5MM) PKG. OUTLINE to PACKAGE OUTLINE, 196L FBGA 15X15X1.5 MM BB196A.	11/20/09	QAD
1	-	*C	3351957	Update spec for sunset review, no changed	8/23/11	QAD
1	-	*D	3722696	ADDED "PKG WEIGHT: REFER TO PMDD SPEC".	8/24/12	QAD

TOP VIEW



BOTTOM VIEW



PKG WEIGHT: REFER TO PMDD SPEC

UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ARE: DECIMALS .XX ± 0.05 .XXX ± .XXXX + MATERIAL N/A FINISH N/A	DESIGNED BY HTN	DATE 05/14/02	CYPRESS Company Confidential TITLE PACKAGE OUTLINE, 196L FBGA 15X15X1.5 MM BB196A SIZE A PART NO. BB196A DWG NO. 51-85156 REV *D SCALED TO FIT N/A SHEET 1 OF 1
	DRAWN BY HTN	DATE 05/14/02	
	CHECKED BY EDCA	DATE 08/24/12	
	APPROVED BY QAD	DATE 08/24/12	
	APPROVED BY ZZQ	DATE 08/24/12	
	APPROVED BY CMG	DATE 08/24/12	

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